



N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BVDSS	Rds(on) Max	I _D Max T _A = +25°C
	0.4Ω @ V _{GS} = 4.5V	1.0A
20V	0.5Ω @ V _{GS} = 2.5V	0.9A
	0.7Ω @ V _{GS} = 1.8V	0.8A

Description and Applications

This MOSFET is designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

Load Switch

Features and Benefits

- Footprint of just 0.6mm² Thirteen Times Smaller than SOT23
- 0.4mm Profile Ideal for Low Profile Applications
- Low Gate Threshold Voltage
- Fast Switching Speed
- **ESD Protected Gate**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMN2450UFB4Q is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

Mechanical Data

- Case: X2-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Lead-Frame. Solderable per MIL-STD-202, Method 208 @4
- Weight: 0.001 grams (Approximate)

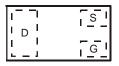
X2-DFN1006-3



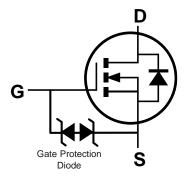
ESD Protected Gate



Bottom View



Top View Internal Schematic



Equivalent Circuit

Ordering Information (Note 4)

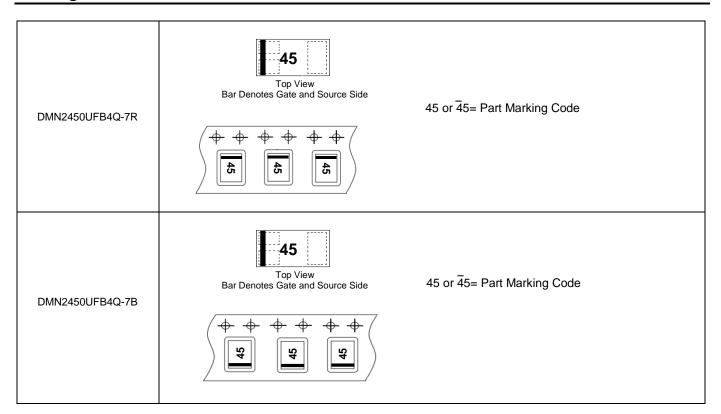
Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Tape Pitch (mm)	Quantity per Reel
DMN2450UFB4Q-7B	45	7	8	2	10,000
DMN2450UFB4Q-7R	45	7	8	4	3,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/



Marking Information





Maximum Ratings (@ T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage			VDSS	20	V
Gate-Source Voltage			V_{GSS}	±12	V
Continuous Drain Current (Note 6) V _{GS} = 4.5V	Steady	$T_A = +25$ °C	lp	1.0	Δ
Continuous Diain Current (Note o) VGS = 4.5V	State	$T_A = +70$ °C	lib lib	0.8	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	3.0	A

Thermal Characteristics (@ TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	PD	0.5	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	225	°C/W
Total Power Dissipation (Note 6)	PD	0.9	W
Thermal Resistance, Junction to Ambient (Note 6)	Reja	129	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

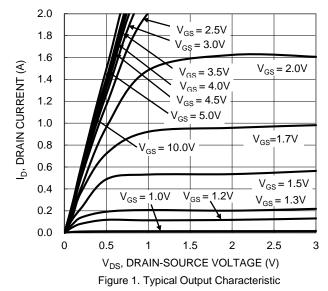
Electrical Characteristics (@ TA = +25°C, unless otherwise specified.)

	T		_				
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	20	_	_	V	$V_{GS} = 0V, I_{D} = 250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	IDSS	_	_	100	nA	V _{DS} = 20V, V _{GS} = 0V	
Gate-Source Leakage	Igss	_	_	±1.0	μΑ	$V_{GS} = \pm 4.5V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	Vgs(TH)	0.5	_	0.9	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
	R _{DS(ON)}	_	0.3	0.4	Ω	$V_{GS} = 4.5V, I_{D} = 600mA$	
Static Drain-Source On-Resistance		_	0.4	0.5		$V_{GS} = 2.5V, I_D = 500mA$	
		-	0.5	0.7		$V_{GS} = 1.8V, I_{D} = 350mA$	
Diode Forward Voltage	VsD	_	0.7	1.2	V	V _G S = 0V, I _S = 150mA	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	_	56	_	pF	101/11/	
Output Capacitance	Coss	_	19	_	pF	V _{DS} =16V, V _{GS} = 0V, -f = 1.0MHz	
Reverse Transfer Capacitance	Crss	1	7.3	_	pF	1 = 1.01/11/12	
Gate Resistance	Rg	_	86	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$	
Total Gate Charge (V _{GS} = 4.5V)	Qg	-	0.6	_	nC		
Total Gate Charge (V _{GS} = 10V)	Qg	_	1.3	_	nC	V _{DS} = 10V, I _D = 250mA	
Gate-Source Charge	Qgs	_	0.1	_	nC		
Gate-Drain Charge	Qgd	_	0.16	_	nC		
Turn-On Delay Time	tD(ON)		5.3	_	ns	10)/ // 15)/	
Turn-On Rise Time	t _R	_	2.6	_	ns	$V_{DD} = 10V, V_{GS} = 4.5V,$	
Turn-Off Delay Time	tD(OFF)		18.1	_	ns	$R_L = 47\Omega$, $R_g = 10\Omega$, $R_D = 200$ mA	
Turn-Off Fall Time	t _F	_	6.6	_	ns	TID = ZOUTIA	

Notes:

- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 25mm X 25mm square copper plate.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.





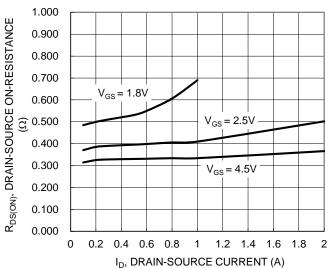


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

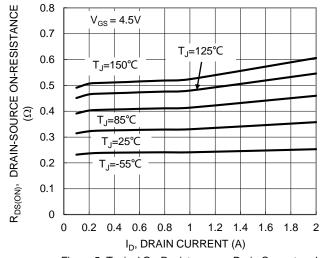


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

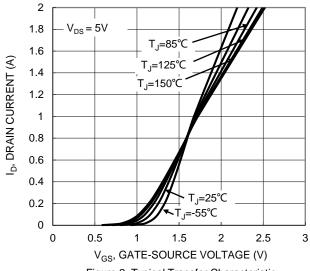
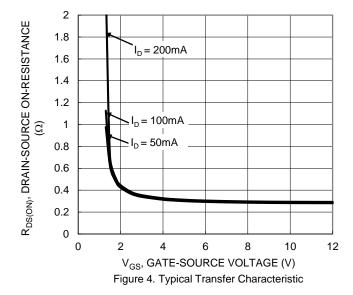


Figure 2. Typical Transfer Characteristic



R_{DS(ON)}, DRAIN-SOURCE ON-RESISTANCE 2 $V_{GS} = 4.5V, I_{D} = 200mA$ 1.8 1.6 $V_{GS} = 2.5V, I_D = 200mA$ 1.4 (NORMALIZED) 1.2 1 0.8 $V_{GS} = 1.8V, I_{D} = 100 \text{mA}$ 0.6 0.4 0.2 0 -50 -25 25 50 75 100 125 150 T_{.I}, JUNCTION TEMPERATURE (°C)

Figure 6. On-Resistance Variation with Temperature



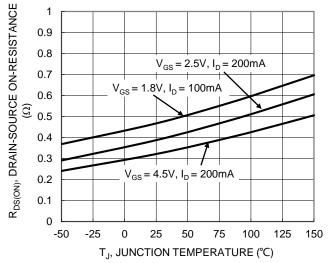


Figure 7. On-Resistance Variation with Temperature

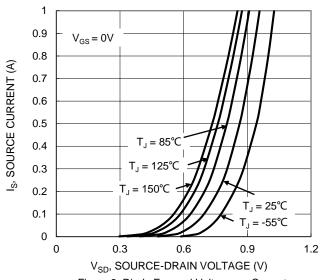


Figure 8. Diode Forward Voltage vs. Current

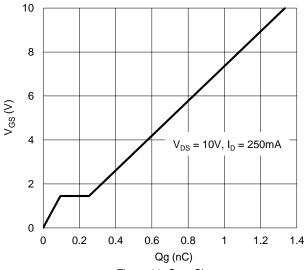


Figure 11. Gate Charge

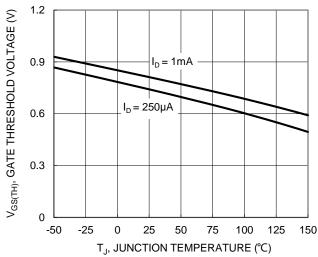
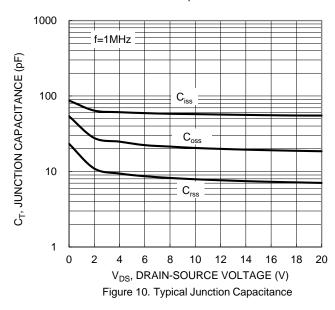


Figure 8. Gate Threshold Variation vs. Junction Temperature



10 R_{DS(ON)} Limited ID, DRAIN CURRENT (A) 1 0.1 $T_{J(Max)} = 150^{\circ}C$ $T_C = 25^{\circ}C$ Single Pulse DUT on 1*MRP Board DC $V_{GS} = 4.5V$ 0.01 0.1 10 100 V_{DS}, DRAIN-SOURCE VOLTAGE (V)

Figure 12. SOA, Safe Operation Area



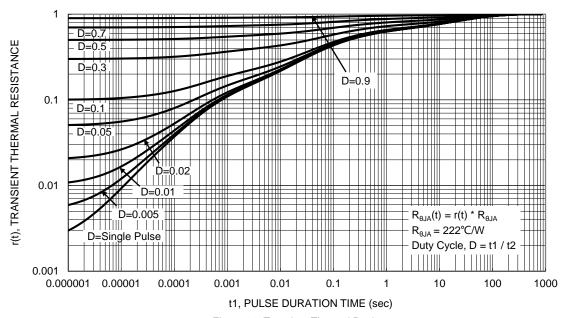


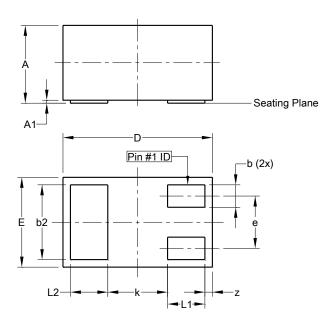
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN1006-3

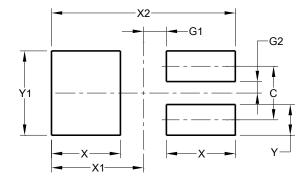


X2-DFN1006-3					
Dim	Min	Max	Тур		
Α	_	0.40			
A 1	0.00	0.05	0.03		
b	0.10	0.20	0.15		
b2	0.45	0.55	0.50		
D	0.95	1.05	1.00		
Е	0.55	0.65	0.60		
е	_		0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
k	_	_	0.40		
Z	0.02	0.08	0.05		
All Dimensions in mm					

Suggested Pad Layout

 $\label{prop:lease} Please see \ http://www.diodes.com/package-outlines.html for the latest version.$

X2-DFN1006-3



Dimensions	Value (in mm)
С	0.350
G1	0.150
G2	0.075
Х	0.450
X1	0.600
X2	1.200
Y	0.200
V1	0.550



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